

Title (en)

Method of pressing contact elements of a high density connector into holes of a printed circuit board and tool for carrying out the method.

Title (de)

Verfahren zum Einpressen von Kontaktelementen hochpoliger Steckverbinder in Leiterplatterbohrungen, sowie Werkzeug zur Durchführung des Verfahrens.

Title (fr)

Procédé pour presser des éléments de contact de connecteurs à haute densité de contact dans des percages de cartes imprimées ainsi que l'outil pour la réalisation du procédé.

Publication

EP 0541025 A2 19930512 (DE)

Application

EP 92118713 A 19921102

Priority

DE 4136853 A 19911108

Abstract (en)

[origin: JPH05217658A] PURPOSE: To provide a method for contact elements of a plug connection member having many poles into a printed wiring board and a method in which force needed for pushing-in is small and which can be executed simply and economically as much as possible. CONSTITUTION: Contact elements 2 are thrust into a hole 4 in a printed wiring board 5 in at least two work steps. In the first work step, a first part of the contact elements, only to which pushing force is applied, are pushed into the hole in the printed wiring board, and then a part 6 to be pushed-in of the contact elements to which pushing force is not applied yet are moved only to an upper range of the hole in the printed wiring board and pushed up into a cutout 8 of an insulating body 7. In the second work step or the subsequent work step, pushing force is applied to all the rest of or part of the pushed-up contact elements and thereby these contact elements are pushed back while the part 6 to be pushed-in are pushed into the hole 4 in the printed wiring board 5.

Abstract (de)

Zum Einpressen der Kontaktelemente hochpoliger Steckverbinder in Leiterplattenbohrungen wird vorgeschlagen, die Kontaktelemente in mehreren Arbeitsschritten nacheinander einzupressen, wobei bei jedem Arbeitsschritt nur so viele Kontaktelemente eingepreßt werden, daß die Einpreßkraft keine übermäßig großen Werte annimmt und mit üblichen Pressen erzeugt werden kann. <IMAGE>

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H01R 43/20

IPC 8 full level

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CPC (source: EP US)

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